## **AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the applications.

## **LISTING OF CLAIMS:**

- 1.-6. (Cancelled)
- 7. (New) A sintering method for a W-Cu composite material without exuding of Cu comprising the steps of:
- (a) preparing a W-Cu composite powder comprised of W and Cu powders prepared by mixing WO<sub>3</sub>/WO<sub>2.9</sub> powder and CuO/Cu<sub>2</sub>O powder;
  - (b) compacting the W-Cu composite powder to a W-Cu composite material;
- (c) densifying the W-Cu composite material by holding the W-Cu composite material at a temperature of about 800 to about 1083°C under a reduction atmosphere; and
- (d) sintering the W-Cu composite material at a temperature ranging from about 1200 to about 1400°C without an isothermal hold.
- 8. (New) The method of claim 7, wherein the densifying step is performed for about 0.5 to about 10 hours.

- 9. (New) A sintering method for a W-Cu composite material without exuding of Cu comprising:
- (a) preparing a W-Cu composite powder comprised of W and Cu powders prepared by mixing WO<sub>3</sub>/WO<sub>2.9</sub> powder and CuO/Cu<sub>2</sub>O powder;
  - (b) compacting the W-Cu composite powder to a W-Cu composite material;
- (c) densifying the W-Cu composite material by holding the W-Cu composite material at a temperature ranging from about 1083 to about 1150°C under a reduction atmosphere; and
- (d) sintering the W-Cu composite material at a temperature ranging from about 1200 to about 1400°C without an isothermal hold.
- 10. (New) The method of claim 9, wherein the densifying step is performed for about 0.5 to about 10 hours.
- 11. (New) The method of claim 7 wherein the W-Cu composite powder formed is round and the W powder surrounds the Cu powder.
- 12. (New) The method of claim 9 wherein the W-Cu composite powder formed is round and the W powder surrounds the Cu powder.